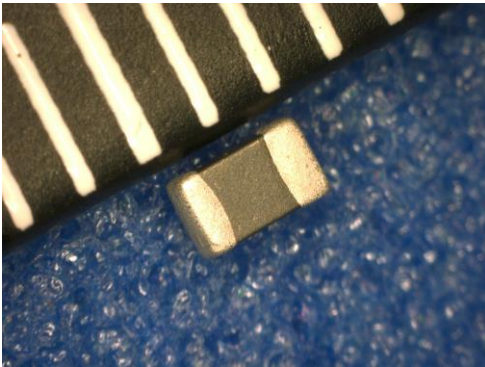


Multi-layer Power Inductor : MIPSZ2012D_Fseries

Features



- 2.0x1.2 mm and 1.0 mm in height (very compact size): CAE and fine printing technology made this compact size possible
- Stable minimum DC resistance in the class
- High speed mounting: Using SMT mounter makes less than a second mounting possible
- Excellent mounting strength by SMD chip making
- Reduced noise over 2/3 of coil inductor by optimal design of CAD
- Completely lead-free product and support lead-free solder

Applications

- DC-DC converters and power modules used for the following equipments. Compact electrical instruments such as cellular phones, DSC, DVC, PDA, DVD and HDD.

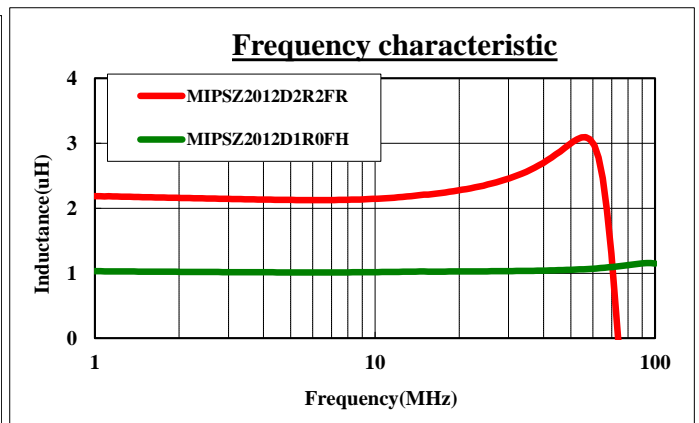
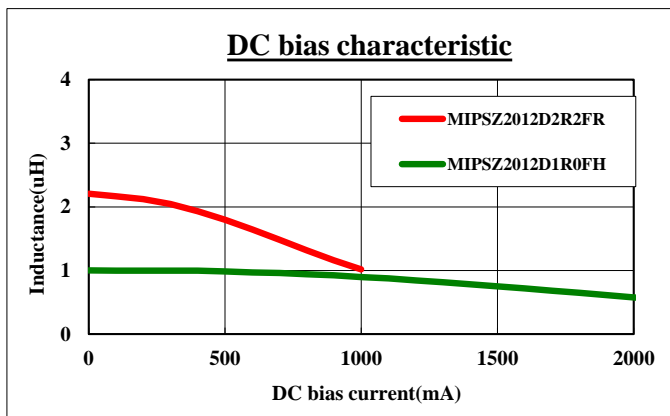
Specifications

Product name	MIPSZ2012D2R2FR	MIPSZ2012D1R0FH
Inductance(uH) at 1MHz	2.2 ± 30%	1.0 ± 30%
DC resistance(ohm)	0.125 ± 30%	0.08 ± 30%
Rated current(A)_typ.*1	1.7	2.0
Rated current(A)_typ.*2	0.7	1.5

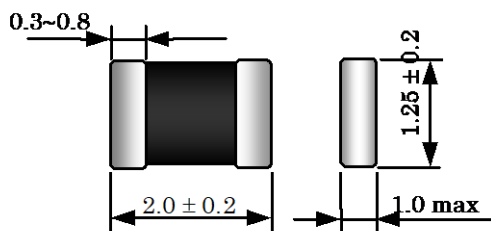
Rated current_*1 : In case temperature rise to 40°C due to self-heating.

Operating temperature range: -40~85°C

Rated current_*2 : The saturation current : L=-30% down from initial L value.



Shapes and Dimensions



Standard package : Emboss taping (reel)

Recommended land pattern

